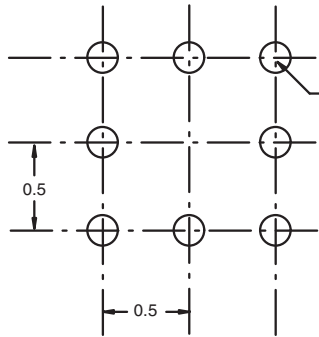
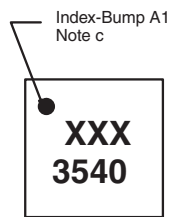
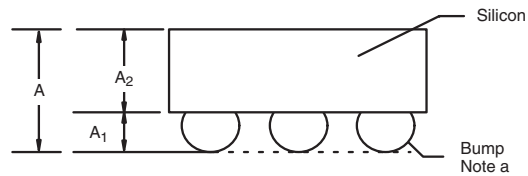


## MICRO FOOT: 8-BUMP (3 mm x 3 mm, 0.5 mm PITCH, 0.238 mm BUMP HEIGHT)

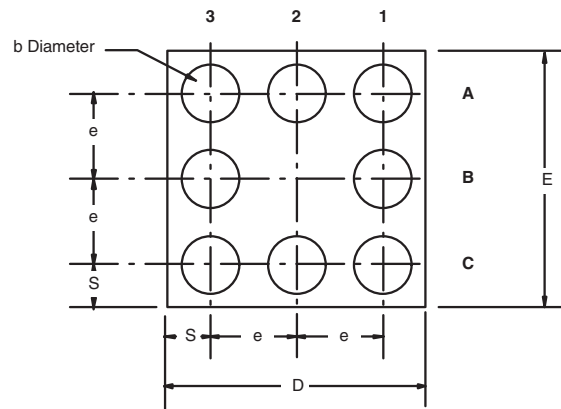


Recommended Land Pattern

8 x  $\varnothing$  0.150  $\square$  0.229  
 Note b  
 Solder Mask  $\varnothing$   $\square$  Pad Diameter + 0.1



Top Side (Die Back)



### Notes

(unless otherwise specified)

- a. Bump is lead (Pb)-free Sn/Ag/Cu.
- b. Non-solder mask defined copper landing pad.
- c. Laser mark on silicon die back; back-lapped, no coating. Shown is not actual marking; sample only.

DIM.	MILLIMETERS <sup>a</sup>		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.688	0.753	0.0271	0.0296
A <sub>1</sub>	0.218	0.258	0.0086	0.0102
A <sub>2</sub>	0.470	0.495	0.0185	0.0195
b	0.306	0.346	0.0120	0.0136
D	1.480	1.520	0.0583	0.0598
E	1.480	1.520	0.0583	0.0598
e	0.5 BASIC		0.0197 BASIC	
S	0.230	0.270	0.0091	0.0106

### Note

- a. Use millimeters as the primary measurement.

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